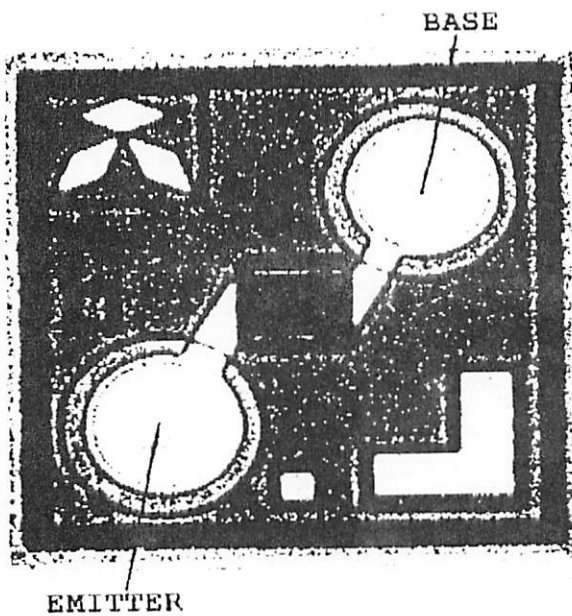


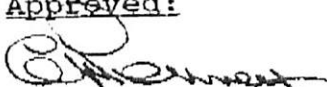
DIE TECHNOLOGY LIMITED



CHIP BACK IS COLLECTOR

Dennis
 Reference your
 purchase order
 11499
 Colin advises that
 Philips BFR90A
 now look like this.
 The HP spec cannot
 be met unless they
 give a concession
 for this layout.
 Please advise
 Regards
 Eric

E & O E. The supply of dice to this layout can only be guaranteed if it forms part of a specification or the chip identification, if below, is requested. Chip back potential is the level at which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated above. If no potential is given the chip back should be isolated. Nominal metallisation thicknesses are based on manufacturer's information. Tolerance on chip dimensions +1.3 mils.

<p><u>Approved:</u>  <u>Date:</u> 28-7-97</p>	<p><u>Metallisation/Thickness(KA)</u> Top : Au 10 Back: AuAs 4</p> <p>Back Potential: Collector Man's. Part No:</p>	<p><u>Chip Identification</u> Line Source: Mask Ref : Process : Version : Geometry :</p>
<p>Corbrook Road Chadderton Lancs. OL9 9SD</p> <p>Tel: 061 626 3827 Fax: 061 627 2341</p>	<p><u>Chip Dimensions (mils.):</u> 11 x 11 x 8</p>	<p><u>Bond Pads:</u> 2.5 ϕ</p>
<p>PHILIPS BFR90A</p>		<p>Issue 2</p>